



### 400V PNP HIGH VOLTAGE SWITCHING TRANSISTOR IN SOT89

#### Features

- BV<sub>CEO</sub> > -400V
- I<sub>C</sub> = -0.5A Continuous Collector Current
- I<sub>CM</sub> = 1A Peak Pulse Current
- High Gain Holds up  $h_{FE} \ge 140$  @  $I_C$  = -100mA
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### Applications

High Voltage Switching

#### **Mechanical Data**

- Case: SOT89
- Case material: molded plastic. "Green" molding compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.05 grams (Approximate)

# Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DA1971-7	1S2	7	12	1,000
2DA1971-13	1S2	13	12	2,500

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

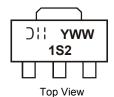
and Lead-free.

Notes:

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



1S2 = Product Type Marking Code YWW = Date Code Marking Y = Last digit of year (ex: 1 = 2011) WW = Week code (01 - 53)



## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-400	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-400	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ι <sub>C</sub>	-0.5	A
Peak Pulse Current	I <sub>CM</sub>	-1	A
Base Current	IB	-250	mA

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	10.4	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

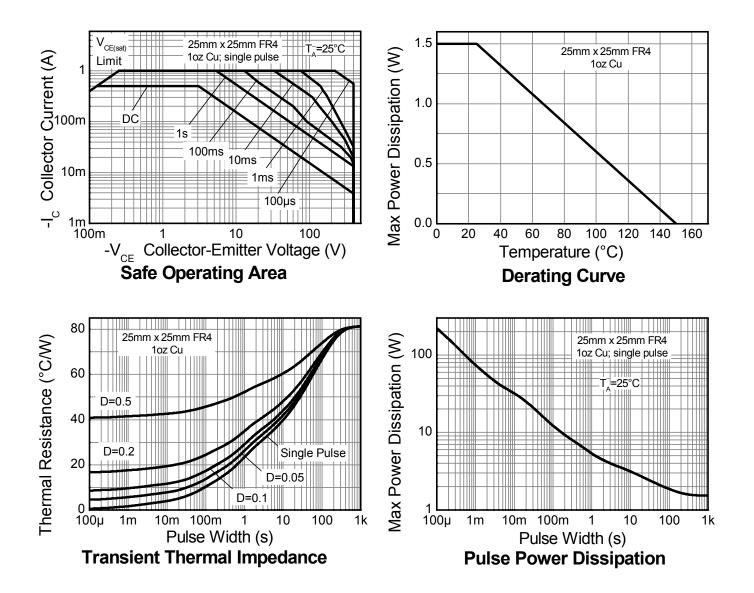
# ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

 For a device mounted with the exposed collector pad on 25mm x 25mm 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
Thermal resistance from junction to solder-point (on the exposed collector pad).
Refer to JEDEC specification JESD22-A114 and JESD22-A115. Notes:



# Thermal Characteristics and Derating information





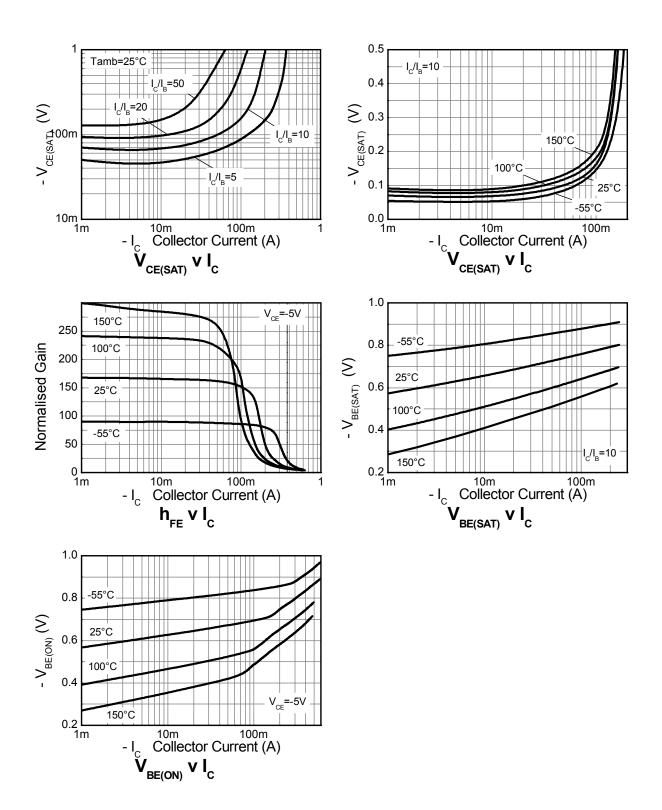
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-400	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-400	-	-	V	I <sub>C</sub> = -1mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector-Emitter Cut-off Current	ICES	-	-	-100	nA	V <sub>CE</sub> = -320V
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -320V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-100	nA	V <sub>EB</sub> = -6V
Static Forward Current Transfer Ratio (Note 8)	h <sub>FE</sub>	140 140	-	450 400	-	I <sub>C</sub> = -20mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -100mA, V <sub>CE</sub> = -5V
Collector-Emitter saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-	-250 -400	mV	$I_{C}$ = -100mA, $I_{B}$ = -10mA $I_{C}$ = -200mA, $I_{B}$ = -40mA
Base-Emitter saturation Voltage (Note 8)	V <sub>BE(sat)</sub>	-	-0.75	-0.9	V	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Base-Emitter Turn-On Current (Note 8)	V <sub>BE(on)</sub>	-	-	-0.8	V	I <sub>C</sub> = -200mA, V <sub>CE</sub> = -10V
Transition frequency	fT	-	75	-	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -5V, f = 50MHz
Collector Output Capacitance	C <sub>obo</sub>	-	19	-	pF	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1MHz
Delay Time	t <sub>(d)</sub>	-	89	-	ns	
Rise Time	t <sub>(r)</sub>	-	111	-	ns	V <sub>CC</sub> = -200V, I <sub>C</sub> = -100mA,
Storage Time	t <sub>(s)</sub>	-	2165	-	ns	I <sub>B1</sub> = -10mA, I <sub>B2</sub> = 20mA
Fall Time	t <sub>(f)</sub>	-	185	-	ns	

Note: 8. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%



# Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

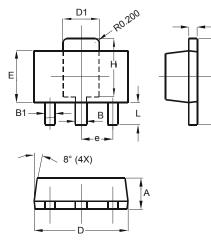




## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

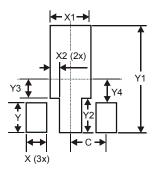
C



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
С	0.35	0.44		
D	4.40	4.60		
D1	1.62	1.83		
Е	2.29	2.60		
e	1.50 Typ			
н	3.94	4.25		
H1	2.63	2.93		
L	0.89	1.20		
All Dimensions in mm				

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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